### SN74ALVCHR162601 18-BIT UNIVERSAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES123E - SEPTEMBER 1997 - REVISED FEBRUARY 1999

- **Member of the Texas Instruments** Widebus™ Family
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- **UBT**<sup>™</sup> (Universal Bus Transceiver) **Combines D-Type Latches and D-Type** Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Mode
- Output Ports Have Equivalent 26- $\Omega$  Series Resistors, So No External Resistors Are Required
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- **Package Options Include Plastic Thin** Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

NOTE: For order entry:

The DGG package is abbreviated to G, and the DGV package is abbreviated to V.

### description

This 18-bit universal bus transceiver is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74ALVCHR162601 combines D-type latches and D-type flip-flops to allow data flow in transparent, latched, clocked, and clock-enabled modes.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (CLKENAB and CLKENBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, CLKBA, and CLKENBA.

The outputs include equivalent 26- $\Omega$  series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



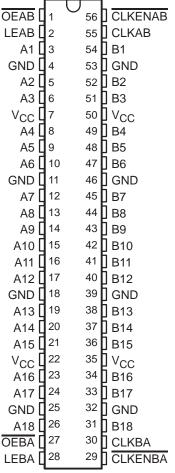
testing of all parameters.

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DGG, DGV, OR DL PACKAGE (TOP VIEW)



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### description (continued)

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

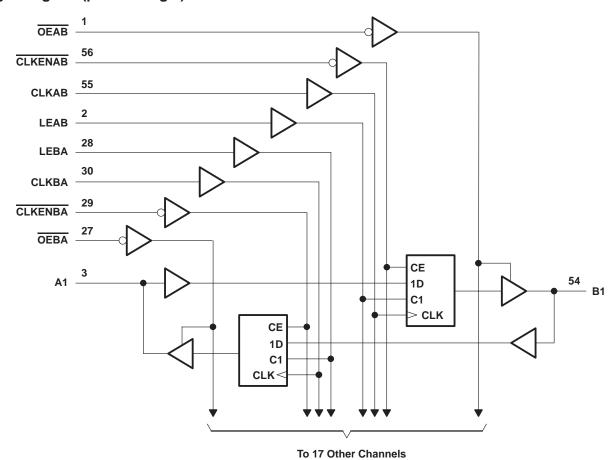
The SN74ALVCHR162601 is characterized for operation from -40°C to 85°C.

### **FUNCTION TABLE**<sup>†</sup>

	OUTPUT				
CLKENAB	OEAB	LEAB	CLKAB	Α	В
Х	Н	Х	Х	Χ	Z
Х	L	Н	Χ	L	L
Х	L	Н	Χ	Н	Н
Н	L	L	Χ	Χ	в <sub>0</sub> ‡
L	L	L	$\uparrow$	L	L
L	L	L	$\uparrow$	Н	Н
L	L	L	L or H	Χ	в <sub>0</sub> ‡

<sup>†</sup> A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, CLKBA, and CLKENBA.

### logic diagram (positive logic)





<sup>‡</sup> Output level before the indicated steady-state input conditions were established

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> : Except I/O ports (see Note 1)	
I/O ports (see Notes 1 and 2)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Output voltage range, VO (see Notes 1 and 2)	0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		1.65	3.6	V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>			
ViH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>		
VIL	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V	
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8		
٧ı	Input voltage	•	0	Vcc	V	
٧o	Output voltage		0	Vcc	V	
		V <sub>CC</sub> = 1.65 V		-2		
	High-level output current	V <sub>CC</sub> = 2.3 V		-6	mA	
IOH		V <sub>CC</sub> = 2.7 V		-8		
		V <sub>CC</sub> = 3 V		-12		
		V <sub>CC</sub> = 1.65 V		2		
	Low-level output current	V <sub>CC</sub> = 2.3 V		6	mA	
IOL		V <sub>CC</sub> = 2.7 V		8		
		V <sub>CC</sub> = 3 V		12		
Δt/Δν	Input transition rise or fall rate	•		10	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	MIN T	YPT MAX	UNIT		
	$I_{OH} = -100 \mu A$	1.65 V to 3.6 V	V <sub>CC</sub> -0.2				
	$I_{OH} = -2 \text{ mA}$	1.65 V	1.2				
	$I_{OH} = -4 \text{ mA}$	2.3 V	1.9				
VOH	I <sub>OH</sub> = -6 mA	2.3 V	1.7		V		
	IOH = -0 IIIA	3 V	2.4				
	I <sub>OH</sub> = -8 mA	2.7 V	2				
	I <sub>OH</sub> = -12 mA	3 V	2				
	$I_{OL} = 100 \mu\text{A}$	1.65 V to 3.6 V		0.2			
	$I_{OL} = 2 \text{ mA}$	1.65 V		0.45	1		
	$I_{OL} = 4 \text{ mA}$	2.3 V		0.4			
VOL	lou - 6 mA	2.3 V		0.55	V		
	IOL = 6 mA	3 V		0.55			
	I <sub>OL</sub> = 8 mA	2.7 V		0.6			
	$I_{OL} = 12 \text{ mA}$	3 V		0.8			
lį	$V_I = V_{CC}$ or GND	3.6 V		±5	μΑ		
	V <sub>I</sub> = 0.58 V	4 GE V	25				
	V <sub>I</sub> = 1.07 V	1.65 V	-25				
	V <sub>I</sub> = 0.7 V	2.3 V	45		1		
I <sub>I</sub> (hold)	V <sub>I</sub> = 1.7 V	2.5 V	-45		μΑ		
	V <sub>I</sub> = 0.8 V	3 V	75		1		
	V <sub>I</sub> = 2 V	3 V	-75				
	$V_{I} = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$	3.6 V		±500			
loz§	$V_O = V_{CC}$ or GND	3.6 V		±10	μΑ		
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		40	μΑ		
ΔlCC	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V		750	μΑ		
C <sub>i</sub> Control inputs	$V_I = V_{CC}$ or GND	3.3 V		4	pF		
C <sub>io</sub> A or B ports	$V_O = V_{CC}$ or GND	3.3 V		8	pF		

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>&</sup>lt;sup>‡</sup> This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

 $<sup>\</sup>$  For I/O ports, the parameter IOZ includes the input leakage current.

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# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

			VCC =	$V_{CC} = 1.8 V$ $V_{CC} = 2 \\ \pm 0.2$			V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock freque	ency			†		150		150		150	MHz	
	Pulse			†		3.3		3.3		3.3			
t <sub>W</sub>	duration			†		3.3		3.3		3.3		ns	
	Setup time	Data before CLK↑		†		2.3		2.4		2.1			
		Setup time I Data before LE↓	CLK high	†		2		1.6		1.6		ns	
t <sub>su</sub>			CLK low	†		1.3		1.2		1.1			
		CLKEN before CLK↑		†		2		2		1.7			
	Hold time	Data after CLK↑		†		0.7		0.7		0.8			
		CLI CLI	CLK high	†		1.3		1.6		1.4			
t <sub>h</sub>		old time Data after LE↓ CLK low	CLK low	†		1.7		2		1.7		ns	
		CLKEN after CLK↑		t		0.3		0.5		0.6			

<sup>†</sup> This information was not available at the time of publication.

## switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM TO (INPUT) (OUTPUT		V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
	(1141 01)	(0011 01)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			†		150		150		150		MHz
	A or B			†	1	4.8		5.1	1	4.4	
<sup>t</sup> pd	LEAB or LEBA	B or A		†	1	5.5		5.8	1	5.1	ns
	CLKAB or CLKBA			†	1.2	5.9		6.3	1.4	5.4	
t <sub>en</sub>	OEAB or OEBA	B or A		†	1.1	6.3		6.6	1.1	5.6	ns
<sup>t</sup> dis	OEAB or OEBA	B or A		†	1	4.2		5.1	1.6	4.7	ns

<sup>†</sup> This information was not available at the time of publication.

### operating characteristics, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT	
	TAKAMETEK	FARAMETER		TYP	TYP	TYP	ONIT
	Power dissipation	Outputs enabled	Cı = 0. f = 10 MHz	†	56	63	pF
Cbq	capacitance	Outputs disabled	$C_L = 0$ , $f = 10 MHz$	†	12	13	þΓ

<sup>†</sup> This information was not available at the time of publication.



### PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V}$

**S1** 

**VCC** 

0 V

**VCC** 

0 V

VCC

V<sub>OL</sub>

V<sub>OH</sub>

- 0 V

V<sub>CC</sub>/2

V<sub>CC</sub>/2

**tPLZ** 

V<sub>OL</sub> + 0.15 V

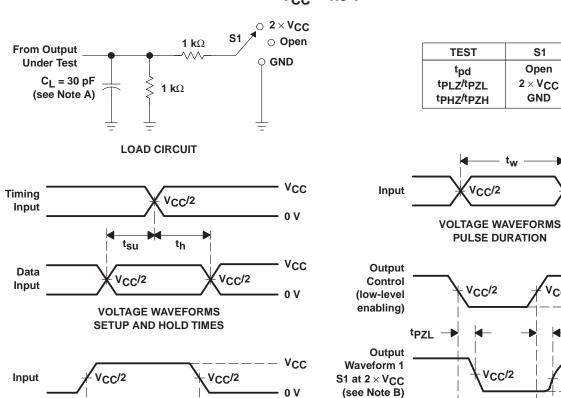
V<sub>OH</sub> - 0.15 V

**tPHZ** 

CC/2

**VOLTAGE WAVEFORMS** 

**ENABLE AND DISABLE TIMES** 



**tPHL** 

V<sub>CC</sub>/2

Vон

VOL

NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

**tPLH** 

Output

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq$  2 ns.  $t_f \leq$  2 ns.

<sup>t</sup>PZH

Output

Waveform 2

(see Note B)

S1 at GND

- D. The outputs are measured one at a time with one transition per measurement.
- tpLZ and tpHZ are the same as tdis.

V<sub>CC</sub>/2

**VOLTAGE WAVEFORMS** 

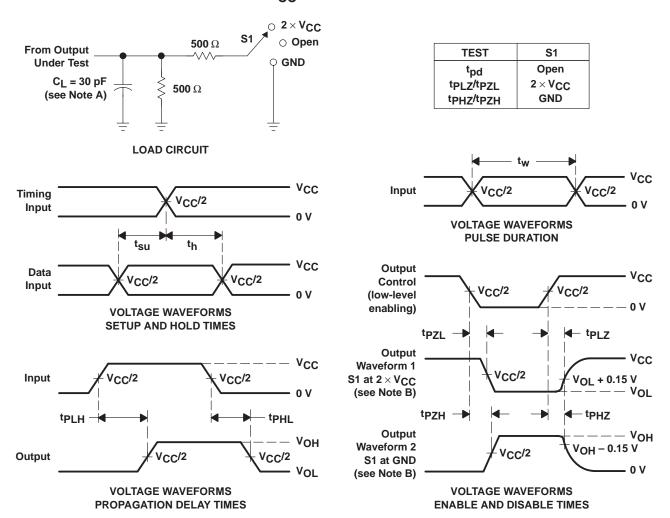
PROPAGATION DELAY TIMES

- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

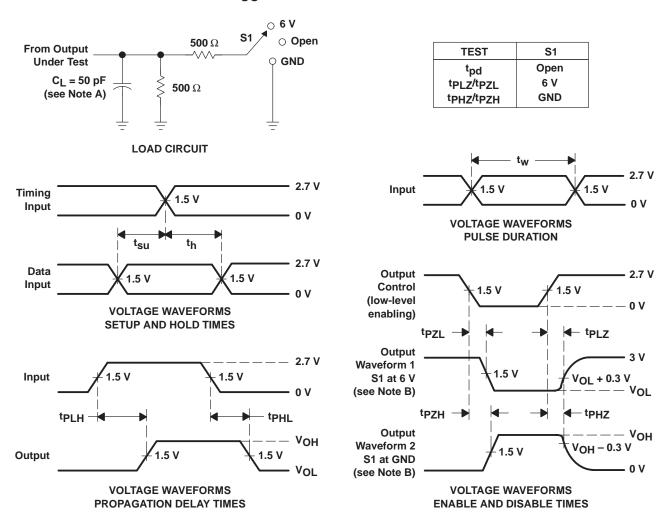


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpz and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



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